MAY 1 7 2002 W

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IN THE UNITED STATE PATENT AND TRADEMARK OFFICE

RACLIFIE application of: MOU-SHIUNG LIN et al.

Application No.: 10/055,560

Filed: January 22,2002

INTEGRATED

CHIP

PACKAGE

STRUCTURE USING METAL SUBSTRATE AND METHOD OF MANUFACTURING THE

SAME

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Examiner:

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

Sir:

Transmitted herewith is a certified copy of Taiwan Application No. <u>90133194</u> filed on <u>December 31, 2001</u>.

A return prepaid postcard is also included herewith.

It is believed no fee is due. However, the Commissioner is authorized to charge any fees required, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 50-0710 (Order No. JCLA8532).

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